

FORM PTO-1449				Atty. Docket No. XA-10063		Appln. No. <i>10/887222</i>	
<b>LIST OF DOCUMENTS CITED BY APPLICANT</b>				Applicant Junji NOGUCHI et al.			
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Examiner Initial		Document Number	Date	Name	Class	Sub-class	Filing Date
<i>[Signature]</i>	AA	6,555,464	04/29/03	Fukada et al.	438	622	
	AB	2002/0127843	09/12/02	Noguchi et al.	438	622	
	AC	2001/0045651	11/29/01	Saito et al.	257	750	
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	AE	2002/0042193	04/11/02	Noguchi et al.	438	618	
	AF	2002/0100984	08/01/02	Oshima et al.	257	774	
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<i>[Signature]</i>	AI	2000-349150	12/15/00	Japan			Abstract
	AJ	2001-53076	02/23/01	Japan			Abstract
	AK	2001-319928	11/16/01	Japan			Abstract
	AL	2001-291720	10/19/01	Japan			Abstract
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	AN	2002-164428	06/07/02	Japan			Abstract
<i>[Signature]</i>	AO	2003-60030	02/28/03	Japan			Abstract
	AP	2003-142579	05/16/03	Japan			Abstract
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<i>[Signature]</i>	AQ	Chiang et al., "TDDB Reliability Improvement in Cu Damascene by using a Bilayer-Structured PECVC SiC Dielectric Barrier", IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002, pp. 200-202.					
Examiner	<i>[Signature]</i>			Date Considered <i>01/21/06</i>			
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.							

<b>FORM PTO-1449</b>				<b>Atty. Docket No.</b> XA-10063		<b>Appln. No.</b> 10/807222	
<b><u>LIST OF DOCUMENTS CITED BY APPLICANT</u></b>				<b>Applicant</b> Junji NOGUCHI et al.			
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<b>Examiner Initial</b>		<b>Document Number</b>	<b>Date</b>	<b>Name</b>	<b>Class</b>	<b>Sub- class</b>	<b>Filing Date</b>
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	BQ						
<b>Examiner</b> [Signature]				<b>Date Considered</b> 01/21/06			
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